

ON Semiconductor®

FDP6030BL/FDB6030BL N-Channel Logic Level PowerTrench[®] MOSFET

Features

General Description

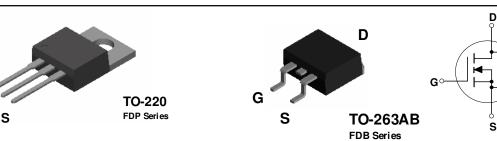
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This N-Channel Logic Level MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

These MOSFETs feature faster switching and lower gate charge than other MOSFETs with comparable $R_{_{DS(on)}}$ specifications resulting in DC/DC power supply designs with higher overall efficiency.

- + 40 A, 30 V. $\rm R_{_{DS(ON)}}$ = 0.018 Ω @ V $_{_{GS}}$ = 10 V $\rm R_{_{DS(ON)}}$ = 0.024 Ω @ V $_{_{GS}}$ = 4.5 V.
- Critical DC electrical parameters specified at elevated temperature.
- Rugged internal source-drain diode can eliminate the need for an external Zener diode transient suppressor.
- High performance trench technology for extremely low $R_{DS(ON)}$.
- 175°C maximum junction temperature rating.



Absolute Maximum Ratings T_c = 25°C unless otherwise noted

| Symbol | Parameter | FDP6030BL | FDB6030BL | Units |
|-----------------------------------|--|-----------|-----------|-------|
| V _{DSS} | Drain-Source Voltage | 30 | | V |
| V _{GSS} | Gate-Source Voltage | ±20 | | V |
| ID | Maximum Drain Current - Continuous (Note 1) | 4 | 0 | Α |
| | - Pulsed | 1 | 20 | |
| PD | Total Power Dissipation @ $T_c = 25^{\circ}C$ | 6 | 60 | W |
| | Derate above 25°C | 0. | 36 | W/°C |
| T _J , T _{STG} | Operating and Storage Junction Temperature Range | -65 to |) +175 | °C |
| Therma | I Characteristics | | | |
| $R_{\theta_{JC}}$ | Thermal Resistance, Junction-to-Case | 2 | .5 | °C/W |
| $R_{\theta_{JA}}$ | Thermal Resistance, Junction-to-Ambient | 62 | 2.5 | °C/W |

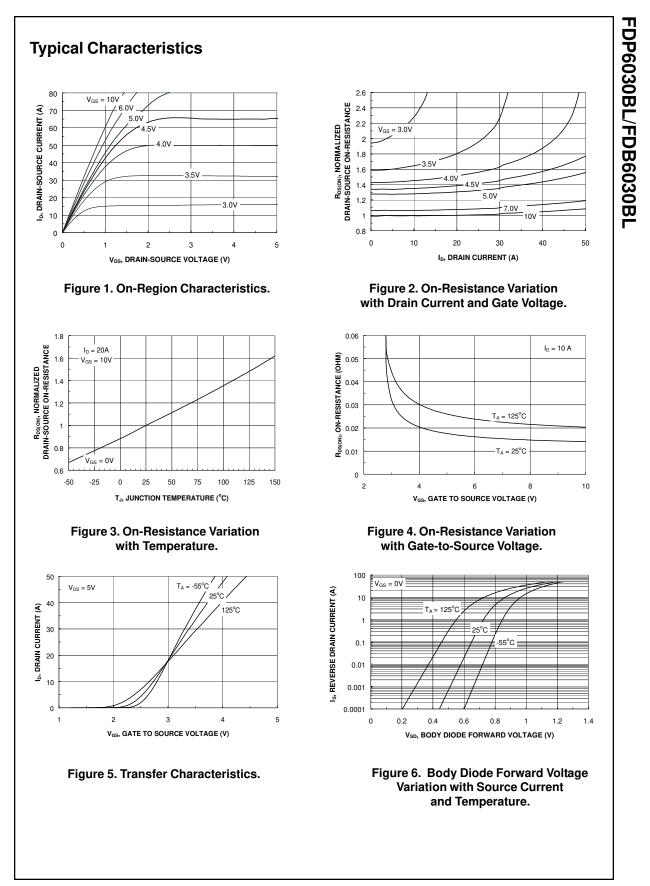
Package Marking and Ordering Information

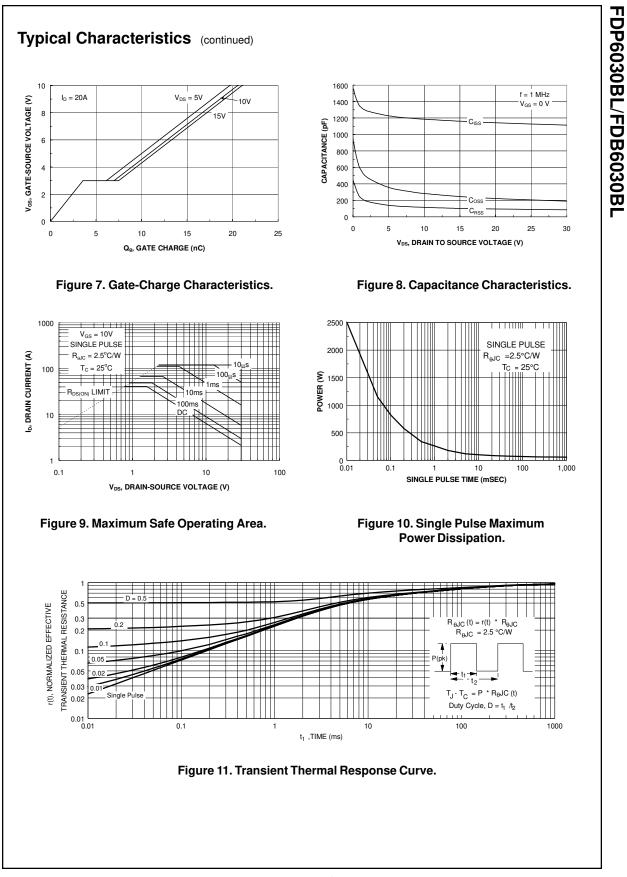
| Device Marking | Device | Reel Size | Tape Width | Quantity |
|----------------|-----------|-----------|------------|----------|
| FDB6030BL | FDB6030BL | 13" | 24mm | 800 |
| FDP6030BL | FDP6030BL | Tube | N/A | 45 |

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| Parameter | Test Conditions | Min | Тур | Max | Unite |
|--|--|--|--|---|--|
| OURCE AVALANCHE RAT | NGS (Note 1) | | | | |
| Single Pulse Drain-Source Avalanche Energy | $V_{DD} = 15 \text{ V}, \text{ I}_{D} = 40 \text{ A}$ | | | 150 | mJ |
| Maximum Drain-Source Avalnche | Current | | | 40 | А |
| acteristics | | | | | |
| Drain-Source Breakdown Voltage | $V_{GS} = 0 V, I_{D} = 250 \mu A$ | 30 | | | V |
| Breakdown Voltage Temperature Coefficient | $I_D = 250 \ \mu\text{A}$, Referenced to 25°C | | 23 | | mV/°C |
| Zero Gate Voltage Drain Current | $V_{\text{DS}} = 24 \text{ V}, V_{\text{GS}} = 0 \text{ V}$ | | | 1 | μA |
| Gate-Body Leakage Current, Forward | $V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$ | | | 100 | nA |
| Gate-Body Leakage Current, Reverse | $V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$ | | | -100 | nA |
| acteristics (Note 1) | | | | | |
| Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = 250 \ \mu A$ | 1 | 1.6 | 3 | V |
| Gate Threshold Voltage Temperature Coefficient | $I_D = 250 \ \mu\text{A}$, Referenced to 25°C | | -4.5 | | mV/°C |
| Static Drain-Source On-Resistance | $V_{GS} = 10 V, I_D = 20 A,$ $V_{GS} = 10 V, I_D = 20 A, T_J = 125^{\circ}C$ $V_{GS} = 4.5 V, I_D = 17 A$ | | 0.015 0.021 0.019 | 0.018 0.030 0.024 | Ω |
| On-State Drain Current | $V_{GS} = 10 \text{ V}, V_{DS} = 10 \text{ V}$ | 40 | | | А |
| Forward Transconductance | $V_{\text{DS}}=5~V,~I_{\text{D}}=20~A$ | | 30 | | S |
| Characteristics | | | | | |
| | $V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ | | 1160 | | pF |
| | f = 1.0 MHz | | 250 | | pF |
| Reverse Transfer Capacitance | | | 100 | | pF |
| • | | | | | |
| | $V_{DD} = 15 V_{c} I_{D} = 1 A_{c}$ | | 9 | 17 | ns |
| Turn-On Rise Time | $V_{GS} = 10 \text{ V}, \text{ R}_{GEN} = 6 \Omega$ | | 11 | 20 | ns |
| | | | 23 | 37 | ns |
| Turn-Off Delay Time | | | | | ns |
| Turn-Off Delay Time Turn-Off Fall Time | | | 8 | 16 | 113 |
| Turn-Off Fall Time | V _{DS} = 15 V, | | 8 12 | 16 17 | nC |
| , , | V _{DS} = 15 V, I _D = 20 A, V _{GS} = 5 V | | 10 | 47 | - |
| Turn-Off Fall Time Total Gate Charge | | | 12 | 47 | nC |
| Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge | I _D = 20 A, V _{GS} = 5 V | | 12 3.2 | 47 | nC nC |
| Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge | $I_D = 20 \text{ A}, V_{GS} = 5 \text{ V}$ and Maximum Ratings | | 12 3.2 | 17 | nC nC nC |
| Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge | $I_D = 20 \text{ A}, V_{GS} = 5 \text{ V}$ and Maximum Ratings | | 12 3.2 | 47 | nC nC |
| | Single Pulse Drain-Source <u>Avalanche Energy</u> Maximum Drain-Source Avalnche acteristics Drain-Source Breakdown Voltage Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate-Body Leakage Current, Forward Gate-Body Leakage Current, Reverse acteristics (Note 1) Gate Threshold Voltage Gate Threshold Voltage Temperature Coefficient Static Drain-Source On-Resistance On-State Drain Current | Avalanche EnergyImage: Constraint of the second systemMaximum Drain-Source Avalnche CurrentacteristicsDrain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}, \text{ I}_D = 250 \text{ µA}$ Breakdown Voltage Temperature $\text{I}_D = 250 \text{ µA}, \text{ Referenced to } 25^{\circ}\text{C}$ Coefficient $\text{V}_D = 250 \text{ µA}, \text{ Referenced to } 25^{\circ}\text{C}$ Zero Gate Voltage Drain Current $V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$ Gate-Body Leakage Current, Forward $V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$ Gate-Body Leakage Current, Reverse $V_{GS} = 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